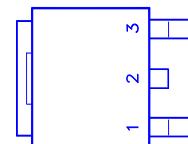
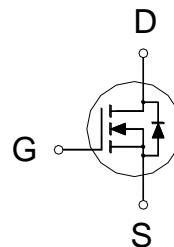


NIKO-SEM
**N-Channel Enhancement Mode
Field Effect Transistor**
P1410BD
TO-252
Halogen-Free & Lead-Free
PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
100V	14.5mΩ	49A

**ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	100	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	49	A
	$T_C = 100^\circ\text{C}$		31	
Pulsed Drain Current ¹		I_{DM}	90	A
Avalanche Current		I_{AS}	20	
Avalanche Energy ²	$L = 1\text{mH}$	E_{AS}	197	
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	83	W
	$T_C = 100^\circ\text{C}$		33	
Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		1.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.
ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	100			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.3	1.8	2.3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$			1	μA
		$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$			10	
Drain-Source On-State Resistance ¹	$R_{DS(\text{ON})}$	$V_{GS} = 4.5\text{V}, I_D = 15\text{A}$		12	16	mΩ
	$R_{DS(\text{ON})}$	$V_{GS} = 10\text{V}, I_D = 20\text{A}$		11.5	14.5	mΩ

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Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 20A$		47		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		4029		pF
Output Capacitance	C_{oss}			269		
Reverse Transfer Capacitance	C_{rss}			219		
Total Gate Charge ²	$Q_g(V_{GS}=10V)$	$V_{DS} = 50V, I_D = 20A$		103		nC
	$Q_g(V_{GS}=4.5V)$			55		
Gate-Source Charge ²	Q_{gs}			15		
Gate-Drain Charge ²	Q_{gd}			34		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DD} = 50V$ $I_D \approx 20A, V_{GS} = 10V, R_{GS} = 6\Omega$		27		nS
Rise Time ²	t_r			36		
Turn-Off Delay Time ²	$t_{d(off)}$			145		
Fall Time ²	t_f			63		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)						
Continuous Current	I_S			69		A
Forward Voltage ¹	V_{SD}	$I_F = 20A, V_{GS} = 0V$			1.2	V
Reverse Recovery Time	t_{rr}	$I_F = 20A, dI_F/dt = 100A / \mu S$		37		nS
Reverse Recovery Charge	Q_{rr}			43		nC

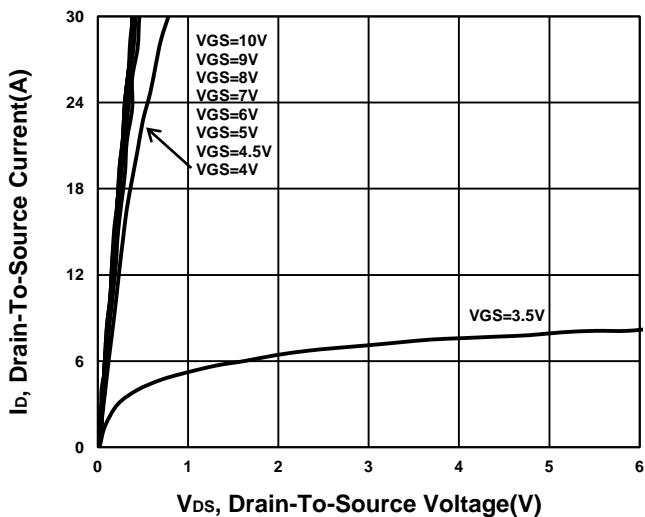
¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.

NIKO-SEM

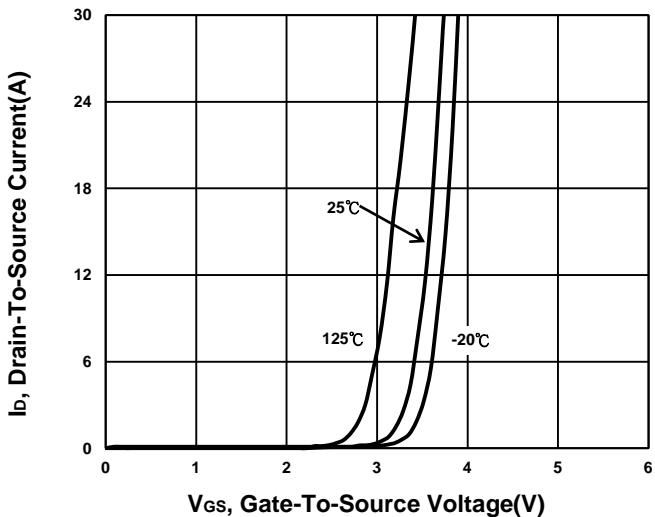
**N-Channel Enhancement Mode
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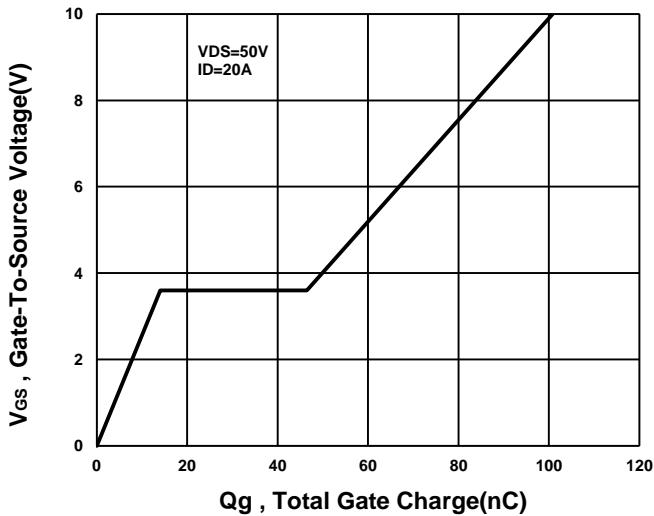
Output Characteristics



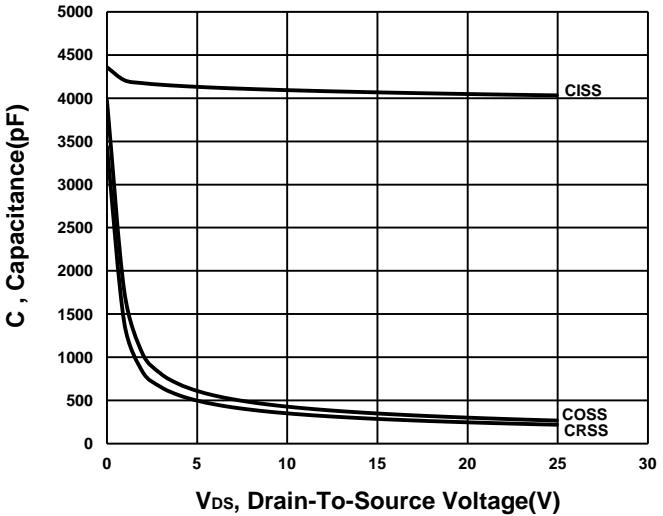
Transfer Characteristics



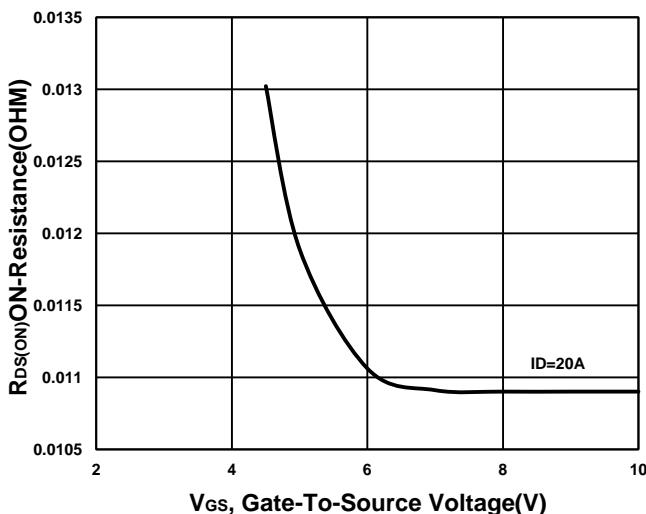
Gate charge Characteristics



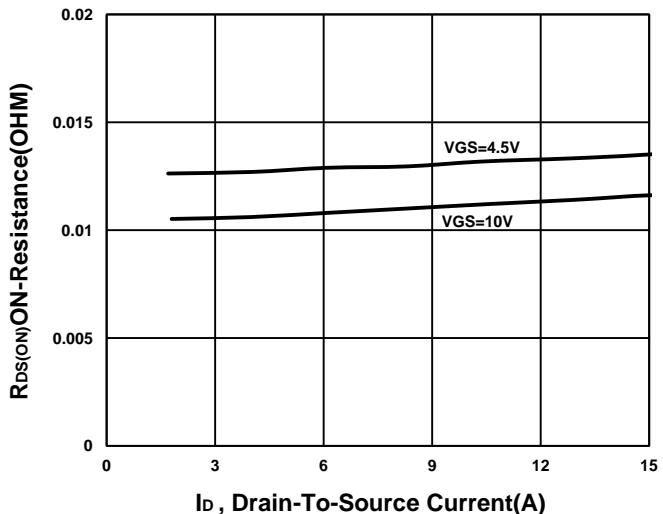
Capacitance Characteristic

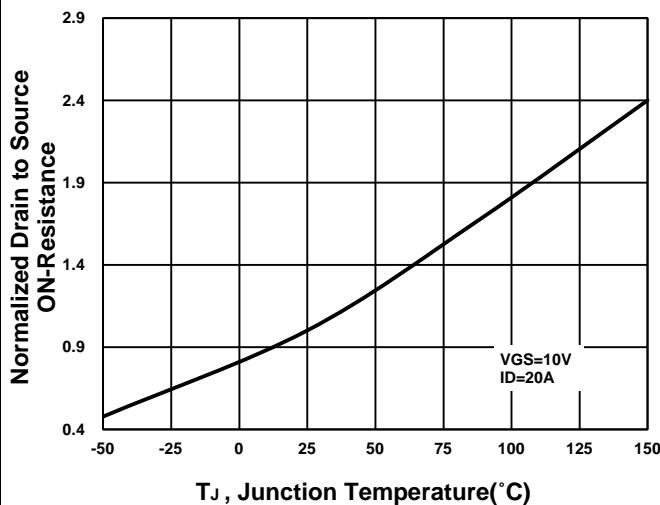
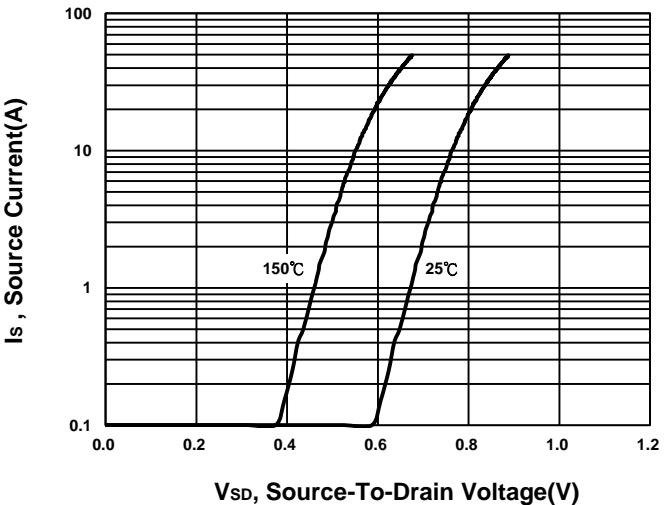
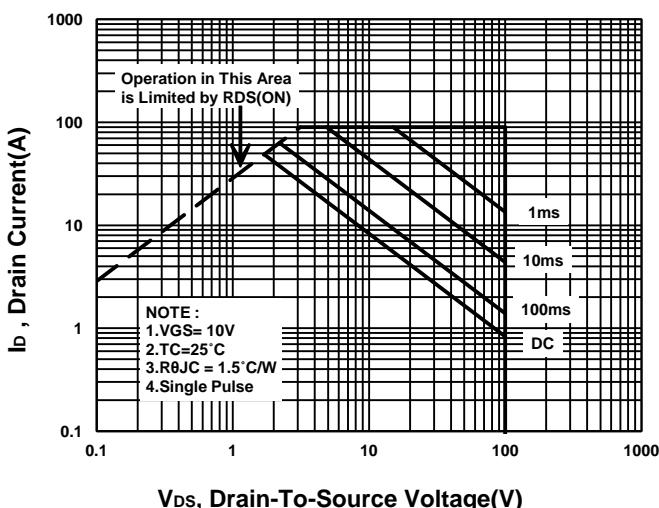
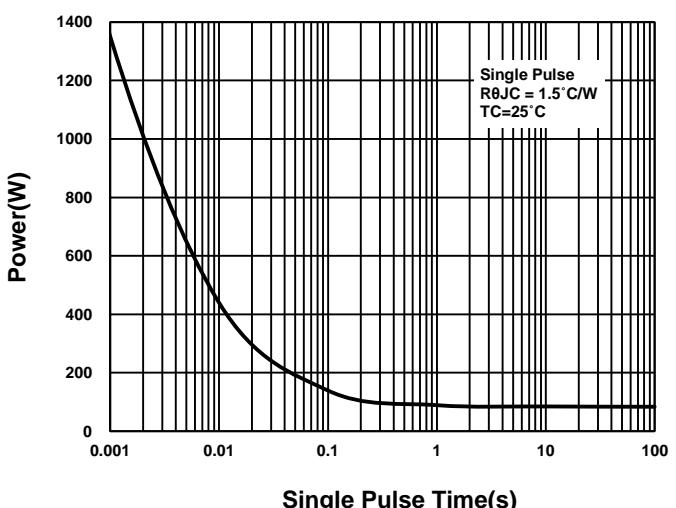


On-Resistance VS Gate-To-Source



On-Resistance VS Drain Current



NIKO-SEM**N-Channel Enhancement Mode
Field Effect Transistor****P1410BD
TO-252
Halogen-Free & Lead-Free****On-Resistance VS Temperature****Source-Drain Diode Forward Voltage****Safe Operating Area****Single Pulse Maximum Power Dissipation****Transient Thermal Response Curve**